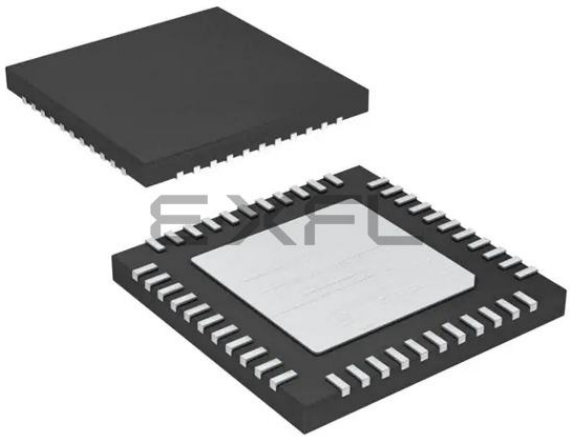

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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Obsolete
Core Processor	PIC
Core Size	8-Bit
Speed	40MHz
Connectivity	I²C, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, LVD, POR, PWM, WDT
Number of I/O	34
Program Memory Size	16KB (8K x 16)
Program Memory Type	FLASH
EEPROM Size	256 x 8
RAM Size	768 x 8
Voltage - Supply (Vcc/Vdd)	4.2V ~ 5.5V
Data Converters	A/D 8x10b
Oscillator Type	External
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	44-VQFN Exposed Pad
Supplier Device Package	44-QFN (8x8)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic18f442t-i-ml

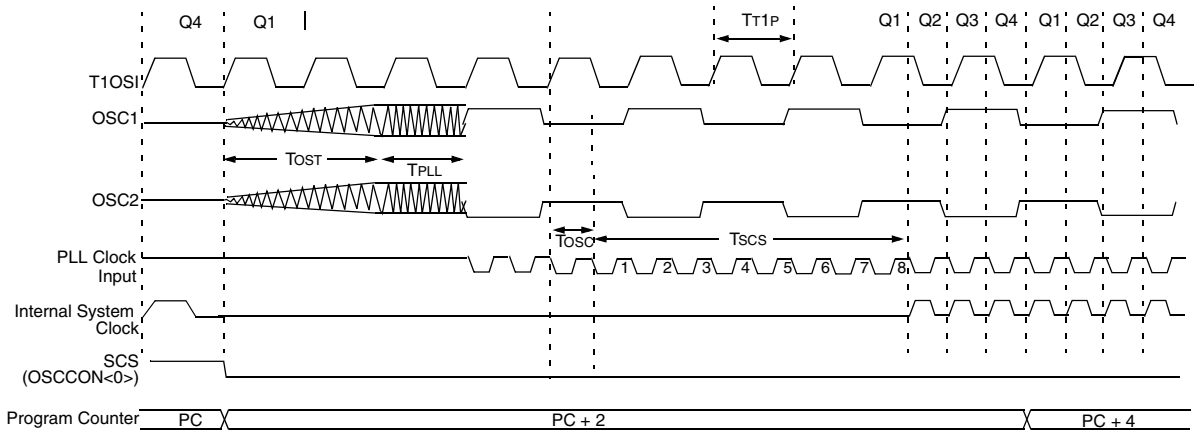
TABLE 1-3: PIC18F4X2 PINOUT I/O DESCRIPTIONS (CONTINUED)

Pin Name	Pin Number			Pin Type	Buffer Type	Description
	DIP	PLCC	TQFP			
						PORTC is a bi-directional I/O port.
RC0/T1OSO/T1CKI	15	16	32			
RC0				I/O	ST	Digital I/O.
T1OSO				O	—	Timer1 oscillator output.
T1CKI				I	ST	Timer1/Timer3 external clock input.
RC1/T1OSI/CCP2	16	18	35			
RC1				I/O	ST	Digital I/O.
T1OSI				I	CMOS	Timer1 oscillator input.
CCP2				I/O	ST	Capture2 input, Compare2 output, PWM2 output.
RC2/CCP1	17	19	36			
RC2				I/O	ST	Digital I/O.
CCP1				I/O	ST	Capture1 input/Compare1 output/PWM1 output.
RC3/SCK/SCL	18	20	37			
RC3				I/O	ST	Digital I/O.
SCK				I/O	ST	Synchronous serial clock input/output for SPI mode.
SCL				I/O	ST	Synchronous serial clock input/output for I^2C mode.
RC4/SDI/SDA	23	25	42			
RC4				I/O	ST	Digital I/O.
SDI				I	ST	SPI Data In.
SDA				I/O	ST	I^2C Data I/O.
RC5/SDO	24	26	43			
RC5				I/O	ST	Digital I/O.
SDO				O	—	SPI Data Out.
RC6/TX/CK	25	27	44			
RC6				I/O	ST	Digital I/O.
TX				O	—	USART Asynchronous Transmit.
CK				I/O	ST	USART Synchronous Clock (see related RX/DT).
RC7/RX/DT	26	29	1			
RC7				I/O	ST	Digital I/O.
RX				I	ST	USART Asynchronous Receive.
DT				I/O	ST	USART Synchronous Data (see related TX/CK).

Legend: TTL = TTL compatible input
CMOS = CMOS compatible input or output
ST = Schmitt Trigger input with CMOS levels
I = Input
O = Output
P = Power
OD = Open Drain (no P diode to V_{DD})

If the main oscillator is configured for HS-PLL mode, an oscillator start-up time (TOST) plus an additional PLL time-out (TPLL) will occur. The PLL time-out is typically 2 ms and allows the PLL to lock to the main oscillator frequency. A timing diagram indicating the transition from the Timer1 oscillator to the main oscillator for HS-PLL mode is shown in Figure 2-10.

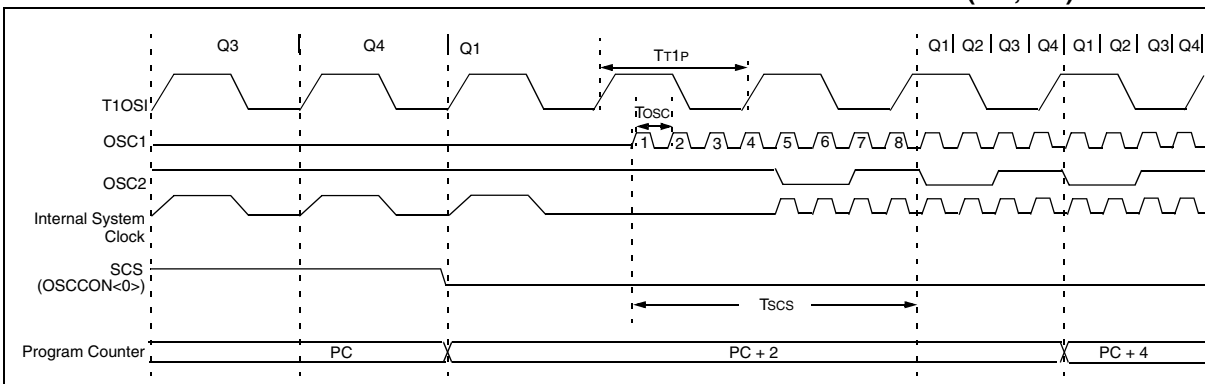
FIGURE 2-10: TIMING FOR TRANSITION BETWEEN TIMER1 AND OSC1 (HS WITH PLL)



Note 1: TOST = 1024 TOSC (drawing not to scale).

If the main oscillator is configured in the RC, RCIO, EC or ECIO modes, there is no oscillator start-up time-out. Operation will resume after eight cycles of the main oscillator have been counted. A timing diagram, indicating the transition from the Timer1 oscillator to the main oscillator for RC, RCIO, EC and ECIO modes, is shown in Figure 2-11.

FIGURE 2-11: TIMING FOR TRANSITION BETWEEN TIMER1 AND OSC1 (RC, EC)



Note 1: RC Oscillator mode assumed.

3.0 RESET

The PIC18FXXX differentiates between various kinds of RESET:

a) Power-on Reset (POR)
b) $\overline{\text{MCLR}}$ Reset during normal operation
c) $\overline{\text{MCLR}}$ Reset during SLEEP
d) Watchdog Timer (WDT) Reset (during normal operation)
e) Programmable Brown-out Reset (BOR)
f) RESETInstruction
g) Stack Full Reset
h) Stack Underflow Reset

Most registers are unaffected by a RESET. Their status is unknown on POR and unchanged by all other RESETS. The other registers are forced to a "RESET state" on Power-on Reset, $\overline{\text{MCLR}}$, WDT Reset, Brown-out Reset, $\overline{\text{MCLR}}$ Reset during SLEEP and by the RESETinstruction.

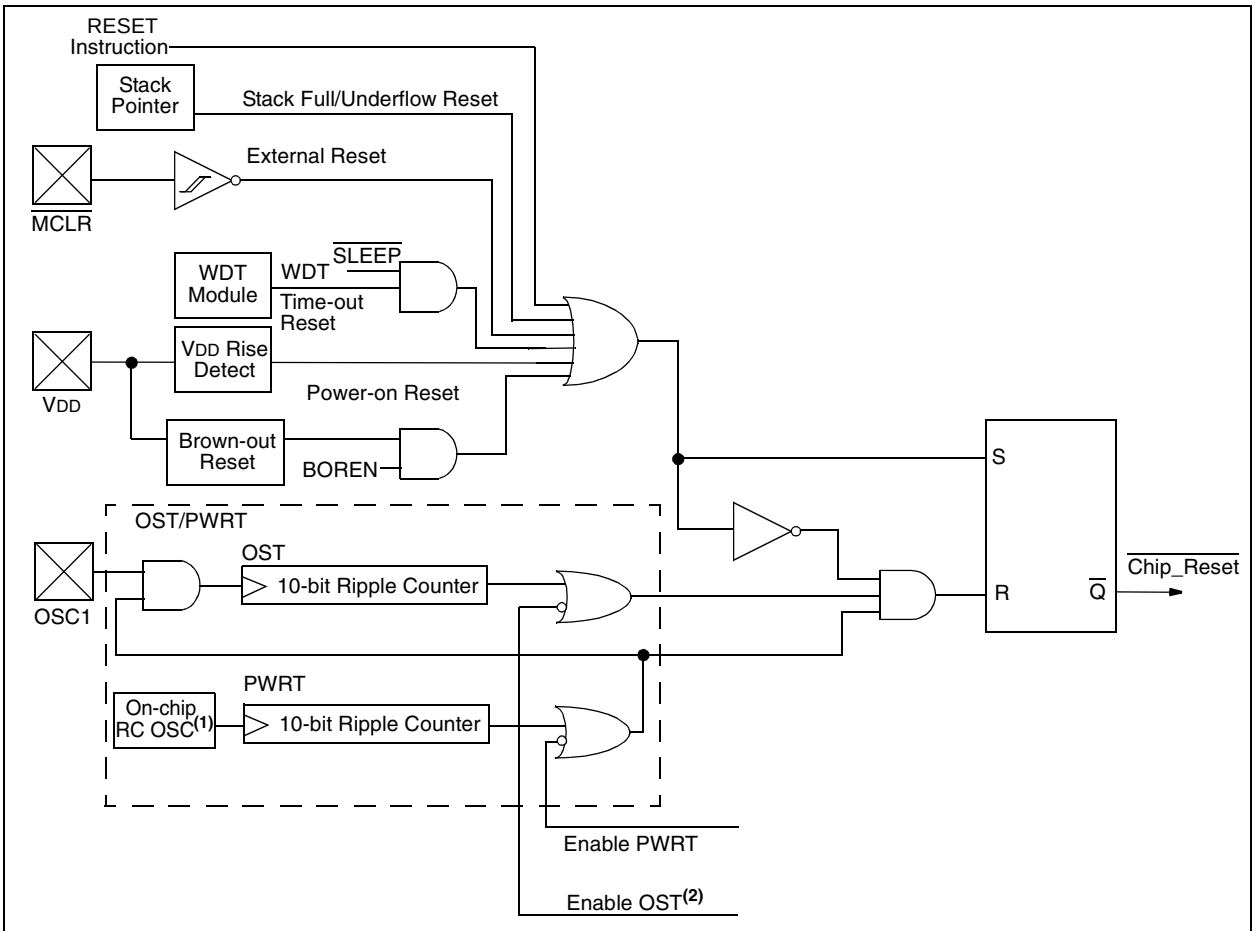
Most registers are not affected by a WDT wake-up, since this is viewed as the resumption of normal operation. Status bits from the RCON register, $\overline{\text{RI}}$, $\overline{\text{TO}}$, $\overline{\text{PD}}$, $\overline{\text{POR}}$ and $\overline{\text{BOR}}$, are set or cleared differently in different RESET situations, as indicated in Table 3-2. These bits are used in software to determine the nature of the RESET. See Table 3-3 for a full description of the RESET states of all registers.

A simplified block diagram of the On-Chip Reset Circuit is shown in Figure 3-1.

The Enhanced MCU devices have a $\overline{\text{MCLR}}$ noise filter in the $\overline{\text{MCLR}}$ Reset path. The filter will detect and ignore small pulses.

The $\overline{\text{MCLR}}$ pin is not driven low by any internal RESETS, including the WDT.

FIGURE 3-1: SIMPLIFIED BLOCK DIAGRAM OF ON-CHIP RESET CIRCUIT



Note 1: This is a separate oscillator from the RC oscillator of the CLKI pin.
2: See Table 3-1 for time-out situations.

4.3 Fast Register Stack

A “fast interrupt return” option is available for interrupts. A Fast Register Stack is provided for the STATUS, WREG and BSR registers and are only one in depth. The stack is not readable or writable and is loaded with the current value of the corresponding register when the processor vectors for an interrupt. The values in the registers are then loaded back into the working registers, if the FAST RETURNinstruction is used to return from the interrupt.

A low or high priority interrupt source will push values into the stack registers. If both low and high priority interrupts are enabled, the stack registers cannot be used reliably for low priority interrupts. If a high priority interrupt occurs while servicing a low priority interrupt, the stack register values stored by the low priority interrupt will be overwritten.

If high priority interrupts are not disabled during low priority interrupts, users must save the key registers in software during a low priority interrupt.

If no interrupts are used, the fast register stack can be used to restore the STATUS, WREG and BSR registers at the end of a subroutine call. To use the fast register stack for a subroutine call, a FAST CALL instruction must be executed.

Example 4-1 shows a source code example that uses the fast register stack.

EXAMPLE 4-1: FAST REGISTER STACK CODE EXAMPLE

```
CALL SUB1, FAST     ;STATUS, WREG, BSR
                    ;SAVED IN FAST REGISTER
                    ;STACK
        €
        €

SUB1    €
        €
        €
    RETURN FAST     ;RESTORE VALUES SAVED
                    ;IN FAST REGISTER STACK
```

4.4 PCL, PCLATH and PCLATU

The program counter (PC) specifies the address of the instruction to fetch for execution. The PC is 21-bits wide. The low byte is called the PCL register. This register is readable and writable. The high byte is called the PCH register. This register contains the PC<15:8> bits and is not directly readable or writable. Updates to the PCH register may be performed through the PCLATH register. The upper byte is called PCU. This register contains the PC<20:16> bits and is not directly readable or writable. Updates to the PCU register may be performed through the PCLATU register.

The PC addresses bytes in the program memory. To prevent the PC from becoming misaligned with word instructions, the LSB of PCL is fixed to a value of ’0’. The PC increments by 2 to address sequential instructions in the program memory.

The CALL, RCALL, GOTO and program branch instructions write to the program counter directly. For these instructions, the contents of PCLATH and PCLATU are not transferred to the program counter.

The contents of PCLATH and PCLATU will be transferred to the program counter by an operation that writes PCL. Similarly, the upper two bytes of the program counter will be transferred to PCLATH and PCLATU by an operation that reads PCL. This is useful for computed offsets to the PC (see Section 4.8.1).

4.5 Clocking Scheme/Instruction Cycle

The clock input (from OSC1) is internally divided by four to generate four non-overlapping quadrature clocks, namely Q1, Q2, Q3 and Q4. Internally, the program counter (PC) is incremented every Q1, the instruction is fetched from the program memory and latched into the instruction register in Q4. The instruction is decoded and executed during the following Q1 through Q4. The clocks and instruction execution flow are shown in Figure 4-4.

FIGURE 4-4: CLOCK/INSTRUCTION CYCLE

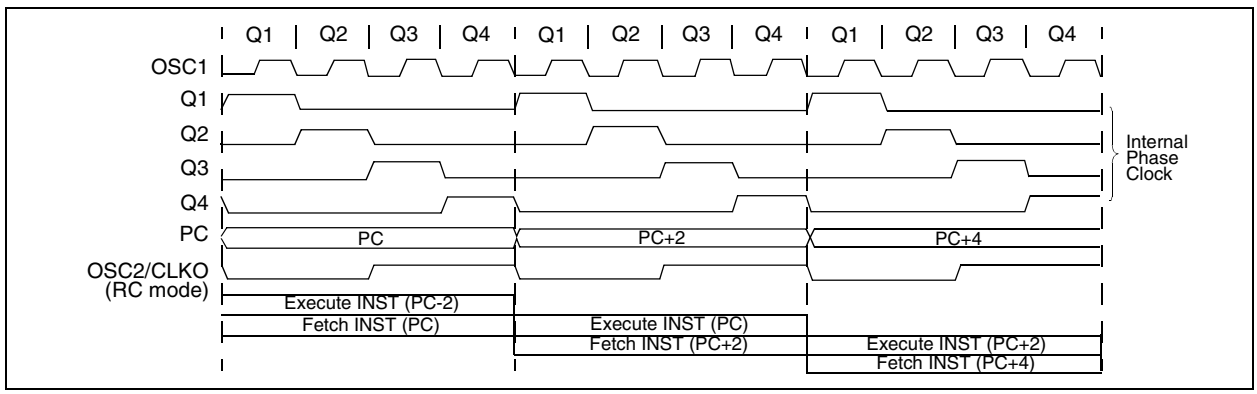


TABLE 11-2: REGISTERS ASSOCIATED WITH TIMER1 AS A TIMER/COUNTER

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on POR, BOR	Value on All Other RESETS
INTCON	GIE/GIEH	PEIE/GIEL	TMR0IE	INT0IE	RBIE	TMR0IF	INT0IF	RBIF	0000 000x	0000 000u
PIR1	PSPIF(1)	ADIF	RCIF	TXIF	SSPIF	CCP1IF	TMR2IF	TMR1IF	0000 0000	0000 0000
PIE1	PSPIE(1)	ADIE	RCIE	TXIE	SSPIE	CCP1IE	TMR2IE	TMR1IE	0000 0000	0000 0000
IPR1	PSPIP(1)	ADIP	RCIP	TXIP	SSPIP	CCP1IP	TMR2IP	TMR1IP	0000 0000	0000 0000
TMR1L	Holding Register for the Least Significant Byte of the 16-bit TMR1 Register								xxxx xxxx	uuuu uuuu
TMR1H	Holding Register for the Most Significant Byte of the 16-bit TMR1 Register								xxxx xxxx	uuuu uuuu
T1CON	RD16	—	T1CKPS1	T1CKPS0	T1OSCEN	T1SYNC	TMR1CS	TMR1ON	0-00 0000	u-uu uuuu

Legend: x = unknown, u = unchanged, - = unimplemented, read as '0'. Shaded cells are not used by the Timer1 module.

Note 1: The PSPIF, PSPIE and PSPIP bits are reserved on the PIC18F2X2 devices; always maintain these bits clear.

REGISTER 15-2: SSPCON1: MSSP CONTROL REGISTER1 (SPI MODE)

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
WCOL	SSPOV	SSPEN	CKP	SSPM3	SSPM2	SSPM1	SSPM0
bit 7							bit 0

bit 7 **WCOL:** Write Collision Detect bit (Transmit mode only)

1 = The SSPBUF register is written while it is still transmitting the previous word (must be cleared in software)

0 = No collision

bit 6 **SSPOV:** Receive Overflow Indicator bit

SPI Slave mode:

1 = A new byte is received while the SSPBUF register is still holding the previous data. In case of overflow, the data in SSPSR is lost. Overflow can only occur in Slave mode.The user must read the SSPBUF, even if only transmitting data, to avoid setting overflow (must be cleared in software).

0 = No overflow

Note: In Master mode, the overflow bit is not set since each new reception (and transmission) is initiated by writing to the SSPBUF register.

bit 5 **SSPEN:** Synchronous Serial Port Enable bit

1 = Enables serial port and configures SCK, SDO, SDI, and $\overline{SS}$ as serial port pins

0 = Disables serial port and configures these pins as I/O port pins

Note: When enabled, these pins must be properly configured as input or output.

bit 4 **CKP:** Clock Polarity Select bit

1 = IDLE state for clock is a high level

0 = IDLE state for clock is a low level

bit 3-0 **SSPM3:SSPM0:** Synchronous Serial Port Mode Select bits

0101 = SPI Slave mode, clock = SCK pin, $\overline{SS}$ pin control disabled, $\overline{SS}$ can be used as I/O pin

0100 = SPI Slave mode, clock = SCK pin, $\overline{SS}$ pin control enabled

0011 = SPI Master mode, clock = TMR2 output/2

0010 = SPI Master mode, clock = FOSC/64

0001 = SPI Master mode, clock = FOSC/16

0000 = SPI Master mode, clock = FOSC/4

Note: Bit combinations not specifically listed here are either reserved, or implemented in I^2C mode only.

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
- n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

REGISTER 15-3: SSPSTAT: MSSP STATUS REGISTER (I²C MODE)

R/W-0	R/W-0	R-0	R-0	R-0	R-0	R-0	R-0
SMP	CKE	D/$\overline{A}$	P	S	R/$\overline{W}$	UA	BF
bit 7							bit 0

bit 7 **SMP:** Slew Rate Control bit
In Master or Slave mode:
1 = Slew rate control disabled for Standard Speed mode (100 kHz and 1 MHz)
0 = Slew rate control enabled for High Speed mode (400 kHz)

bit 6 **CKE:** SMBus Select bit
In Master or Slave mode:
1 = Enable SMBus specific inputs
0 = Disable SMBus specific inputs

bit 5 **D/$\overline{A}$:** Data/$\overline{Address}$ bit
In Master mode:
Reserved
In Slave mode:
1 = Indicates that the last byte received or transmitted was data
0 = Indicates that the last byte received or transmitted was address

bit 4 **P:** STOP bit
1 = Indicates that a STOP bit has been detected last
0 = STOP bit was not detected last
Note: This bit is cleared on RESET and when SSPEN is cleared.

bit 3 **S:** START bit
1 = Indicates that a start bit has been detected last
0 = START bit was not detected last
Note: This bit is cleared on RESET and when SSPEN is cleared.

bit 2 **R/$\overline{W}$:** Read/Write bit Information (I²C mode only)
In Slave mode:
1 = Read
0 = Write
Note: This bit holds the R/W bit information following the last address match. This bit is only valid from the address match to the next START bit, STOP bit, or not $\overline{ACK}$ bit.
In Master mode:
1 = Transmit is in progress
0 = Transmit is not in progress
Note: ORing this bit with SEN, RSEN, PEN, RCEN, or ACKEN will indicate if the MSSP is in IDLE mode.

bit 1 **UA:** Update Address (10-bit Slave mode only)
1 = Indicates that the user needs to update the address in the SSPADD register
0 = Address does not need to be updated

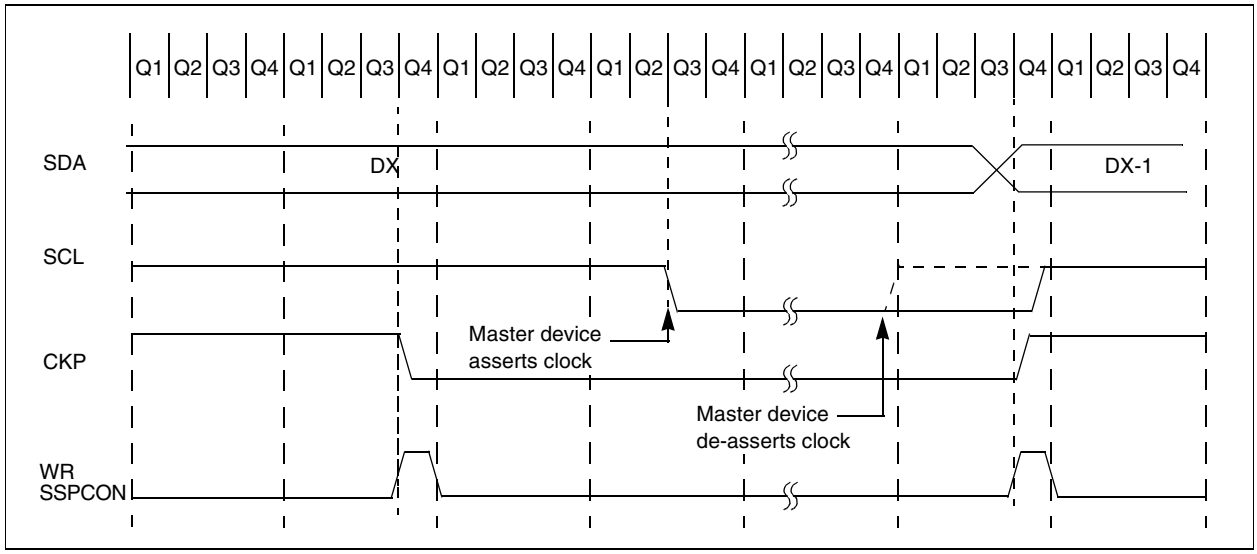
bit 0 **BF:** Buffer Full Status bit
In Transmit mode:
1 = Receive complete, SSPBUF is full
0 = Receive not complete, SSPBUF is empty
In Receive mode:
1 = Data transmit in progress (does not include the $\overline{ACK}$ and STOP bits), SSPBUF is full
0 = Data transmit complete (does not include the $\overline{ACK}$ and STOP bits), SSPBUF is empty

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
- n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

15.4.4.5 Clock Synchronization and the CKP bit

If a user clears the CKP bit, the SCL output is forced to '0'. Setting the CKP bit will not assert the SCL output low until the SCL output is already sampled low. If the user attempts to drive SCL low, the CKP bit will not assert the SCL line until an external I^2C master device has already asserted the SCL line. The SCL output will remain low until the CKP bit is set, and all other devices on the I^2C bus have de-asserted SCL. This ensures that a write to the CKP bit will not violate the minimum high time requirement for SCL (see Figure 15-12).

FIGURE 15-12: CLOCK SYNCHRONIZATION TIMING



15.4.6.1 I²C Master Mode Operation

The master device generates all of the serial clock pulses and the START and STOP conditions. A transfer is ended with a STOP condition or with a Repeated START condition. Since the Repeated START condition is also the beginning of the next serial transfer, the I²C bus will not be released.

In Master Transmitter mode, serial data is output through SDA, while SCL outputs the serial clock. The first byte transmitted contains the slave address of the receiving device (7 bits) and the Read/Write (R/$\overline{W}$) bit. In this case, the R/$\overline{W}$ bit will be logic '0'. Serial data is transmitted 8 bits at a time. After each byte is transmitted, an Acknowledge bit is received. START and STOP conditions are output to indicate the beginning and the end of a serial transfer.

In Master Receive mode, the first byte transmitted contains the slave address of the transmitting device (7 bits) and the R/$\overline{W}$ bit. In this case, the R/$\overline{W}$ bit will be logic '1'. Thus, the first byte transmitted is a 7-bit slave address followed by a '1' to indicate receive bit. Serial data is received via SDA, while SCL outputs the serial clock. Serial data is received 8 bits at a time. After each byte is received, an Acknowledge bit is transmitted. START and STOP conditions indicate the beginning and end of transmission.

The baud rate generator used for the SPI mode operation is used to set the SCL clock frequency for either 100 kHz, 400 kHz or 1 MHz I²C operation. See Section 15.4.7 (“Baud Rate Generator”), for more detail.

A typical transmit sequence would go as follows:

1. The user generates a START condition by setting the START enable bit, SEN (SSPCON2<0>).
2. SSPIF is set. The MSSP module will wait the required start time before any other operation takes place.
3. The user loads the SSPBUF with the slave address to transmit.
4. Address is shifted out the SDA pin until all 8 bits are transmitted.
5. The MSSP Module shifts in the ACK bit from the slave device and writes its value into the SSPCON2 register (SSPCON2<6>).
6. The MSSP module generates an interrupt at the end of the ninth clock cycle by setting the SSPIF bit.
7. The user loads the SSPBUF with eight bits of data.
8. Data is shifted out the SDA pin until all 8 bits are transmitted.
9. The MSSP Module shifts in the ACK bit from the slave device and writes its value into the SSPCON2 register (SSPCON2<6>).
10. The MSSP module generates an interrupt at the end of the ninth clock cycle by setting the SSPIF bit.
11. The user generates a STOP condition by setting the STOP enable bit PEN (SSPCON2<2>).
12. Interrupt is generated once the STOP condition is complete.

16.4.2 USART SYNCHRONOUS SLAVE RECEPTION

The operation of the Synchronous Master and Slave modes is identical, except in the case of the SLEEP mode and bit SREN, which is a “don't care” in Slave mode.

If receive is enabled by setting bit CREN prior to the SLEEPinstruction, then a word may be received during SLEEP. On completely receiving the word, the RSR register will transfer the data to the RCREG register, and if enable bit RCIE bit is set, the interrupt generated will wake the chip from SLEEP. If the global interrupt is enabled, the program will branch to the interrupt vector.

To set up a Synchronous Slave Reception:

1. Enable the synchronous master serial port by setting bits SYNC and SPEN and clearing bit CSRC.
2. If interrupts are desired, set enable bit RCIE.
3. If 9-bit reception is desired, set bit RX9.
4. To enable reception, set enable bit CREN.
5. Flag bit RCIF will be set when reception is complete. An interrupt will be generated if enable bit RCIE was set.
6. Read the RCSTA register to get the ninth bit (if enabled) and determine if any error occurred during reception.
7. Read the 8-bit received data by reading the RCREG register.
8. If any error occurred, clear the error by clearing bit CREN.
9. If using interrupts, ensure that the GIE and PEIE bits in the INTCON register (INTCON<7:6>) are set.

TABLE 16-11: REGISTERS ASSOCIATED WITH SYNCHRONOUS SLAVE RECEPTION

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on POR, BOR	Value on All Other RESETS
INTCON	GIE/ GIEH	PEIE/ GIEL	TMR0IE	INT0IE	RBIE	TMR0IF	INT0IF	RBIF	0000 000x	0000 000u
PIR1	PSPIF(1)	ADIF	RCIF	TXIF	SSPIF	CCP1IF	TMR2IF	TMR1IF	0000 0000	0000 0000
PIE1	PSPIE(1)	ADIE	RCIE	TXIE	SSPIE	CCP1IE	TMR2IE	TMR1IE	0000 0000	0000 0000
IPR1	PSPIP(1)	ADIP	RCIP	TXIP	SSPIP	CCP1IP	TMR2IP	TMR1IP	0000 0000	0000 0000
RCSTA	SPEN	RX9	SREN	CREN	ADDEN	FERR	OERR	RX9D	0000 -00x	0000 -00x
RCREG	USART Receive Register								0000 0000	0000 0000
TXSTA	CSRC	TX9	TXEN	SYNC	—	BRGH	TRMT	TX9D	0000 -010	0000 -010
SPBRG	Baud Rate Generator Register								0000 0000	0000 0000

Legend: x = unknown, - = unimplemented, read as '0'.
Shaded cells are not used for Synchronous Slave Reception.

Note 1: The PSPIF, PSPIE and PSPIP bits are reserved on the PIC18F2X2 devices; always maintain these bits clear.

NEGF **Negate f**

Syntax: [*label*] NEGF f [,a]

Operands: 0 f 255
a [0,1]

Operation: ($\overline{f}$) + 1 f

Status Affected: N, OV, C, DC, Z

Encoding:

0110	110a	ffff	ffff

Description: Location ‘f’ is negated using two’s complement. The result is placed in the data memory location 'f'. If ’a’ is 0, the Access Bank will be selected, overriding the BSR value. If ’a’ = 1, then the bank will be selected as per the BSR value.

Words: 1

Cycles: 1

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read register 'f'	Process Data	Write register 'f'

Example: NEGF REG, 1

Before Instruction
REG = 0011 1010 [0x3A]
After Instruction
REG = 1100 0110 [0xC6]

NOP **No Operation**

Syntax: [*label*] NOP

Operands: None

Operation: No operation

Status Affected: None

Encoding:

0000 1111	0000 xxxx	0000 xxxx	0000 xxxx

Description: No operation.

Words: 1

Cycles: 1

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	No operation	No operation	No operation

Example:

None.

SLEEP **Enter SLEEP mode**

Syntax: [*label*] SLEEP

Operands: None

Operation: 00h WDT,
0 WDT postscaler,
1 $\overline{TO}$,
0 $\overline{PD}$

Status Affected: $\overline{TO}$, $\overline{PD}$

Encoding:

0000	0000	0000	0011

Description: The power-down status bit ($\overline{PD}$) is cleared. The time-out status bit ($\overline{TO}$) is set. Watchdog Timer and its postscaler are cleared.
The processor is put into SLEEP mode with the oscillator stopped.

Words: 1

Cycles: 1

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	No operation	Process Data	Go to sleep

Example: SLEEP

Before Instruction
$\overline{TO}$ = ?
$\overline{PD}$ = ?

After Instruction
$\overline{TO}$ = 1 †
$\overline{PD}$ = 0

† If WDT causes wake-up, this bit is cleared.

SUBFWB **Subtract f from W with borrow**

Syntax: [*label*] SUBFWB f [,d [,a]

Operands: 0 f 255
d [0,1]
a [0,1]

Operation: (W) – (f) – ($\overline{C}$) dest

Status Affected: N, OV, C, DC, Z

Encoding:

0101	01da	ffff	ffff

Description: Subtract register 'f' and carry flag (borrow) from W (2's complement method). If 'd' is 0, the result is stored in W. If 'd' is 1, the result is stored in register 'f' (default). If 'a' is 0, the Access Bank will be selected, overriding the BSR value. If 'a' is 1, then the bank will be selected as per the BSR value (default).

Words: 1

Cycles: 1

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read register 'f'	Process Data	Write to destination

Example 1: SUBFWB REG, 1, 0

Before Instruction
REG = 3
W = 2
C = 1

After Instruction
REG = FF
W = 2
C = 0
Z = 0
N = 1 ; result is negative

Example 2: SUBFWB REG, 0, 0

Before Instruction
REG = 2
W = 5
C = 1

After Instruction
REG = 2
W = 3
C = 1
Z = 0
N = 0 ; result is positive

Example 3: SUBFWB REG, 1, 0

Before Instruction
REG = 1
W = 2
C = 0

After Instruction
REG = 0
W = 2
C = 1
Z = 1 ; result is zero
N = 0

TABLE 22-21: A/D CONVERTER CHARACTERISTICS: PIC18FXX2 (INDUSTRIAL, EXTENDED) PIC18LFXX2 (INDUSTRIAL)

Param No.	Symbol	Characteristic	Min	Typ	Max	Units	Conditions
A01	NR	Resolution	—	—	10	bit	
A03	EIL	Integral linearity error	—	—	<±1	LSb	VREF = VDD = 5.0V
A04	EDL	Differential linearity error	—	—	<±1	LSb	VREF = VDD = 5.0V
A05	EG	Gain error	—	—	<±1	LSb	VREF = VDD = 5.0V
A06	EOFF	Offset error	—	—	<±1.5	LSb	VREF = VDD = 5.0V
A10	—	Monotonicity	guaranteed(2)			—	VSS VAIN VREF
A20	VREF	Reference Voltage	1.8V	—	—	V	VDD < 3.0V
A20A		(VREFH – VREFL)	3V	—	—	V	VDD 3.0V
A21	VREFH	Reference voltage High	AVSS	—	AVDD + 0.3V	V	
A22	VREFL	Reference voltage Low	AVSS – 0.3V	—	VREFH	V	
A25	VAIN	Analog input voltage	AVSS – 0.3V	—	AVDD + 0.3V	V	VDD 2.5V **(Note 3)**
A30	ZAIN	Recommended impedance of analog voltage source	—	—	2.5	k	**(Note 4)**
A50	IREF	VREF input current **(Note 1)**	—	—	5	µA	During VAIN acquisition
			—	—	150	µA	During A/D conversion cycle

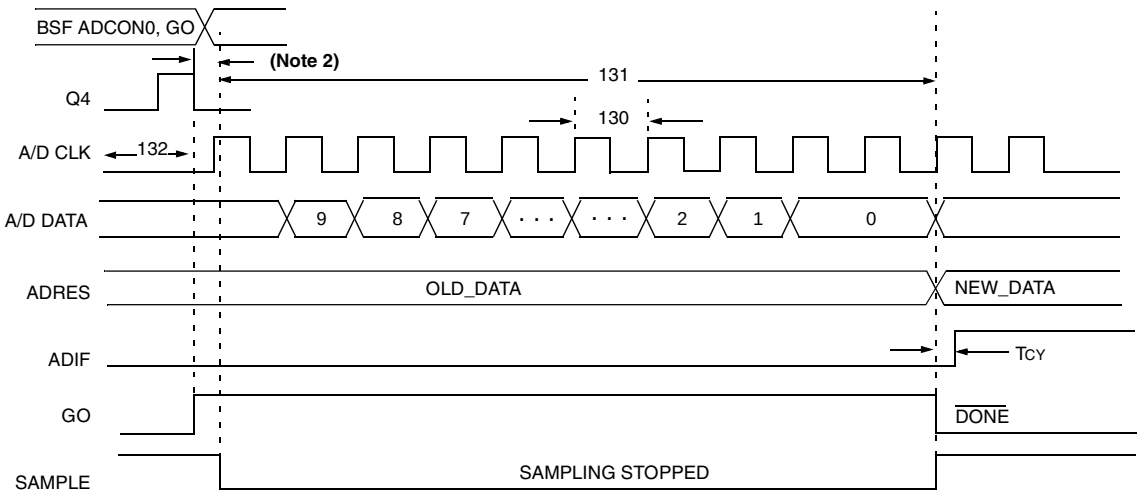
Note 1: VSS VAIN VREF

2: The A/D conversion result never decreases with an increase in the Input Voltage, and has no missing codes.

3: For VDD < 2.5V, VAIN should be limited to < .5 VDD.

4: Maximum allowed impedance for analog voltage source is 10 k . This requires higher acquisition times.

FIGURE 22-22: A/D CONVERSION TIMING



Note 1: If the A/D clock source is selected as RC, a time of TCY is added before the A/D clock starts. This allows the SLEEP instruction to be executed.

2: This is a minimal RC delay (typically 100 nS), which also disconnects the holding capacitor from the analog input.

FIGURE 23-5: TYPICAL IDD vs. FOSC OVER VDD (XT MODE)

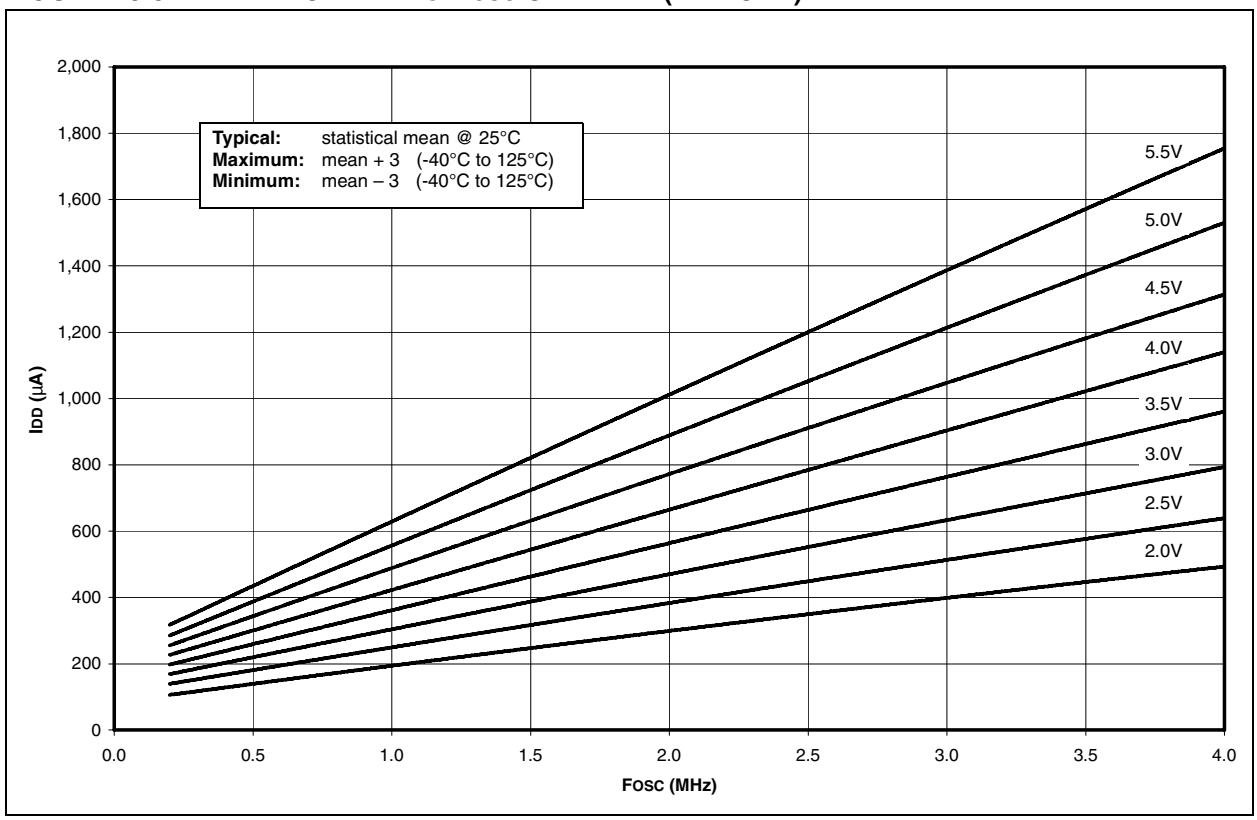


FIGURE 23-6: MAXIMUM IDD vs. FOSC OVER VDD (XT MODE)

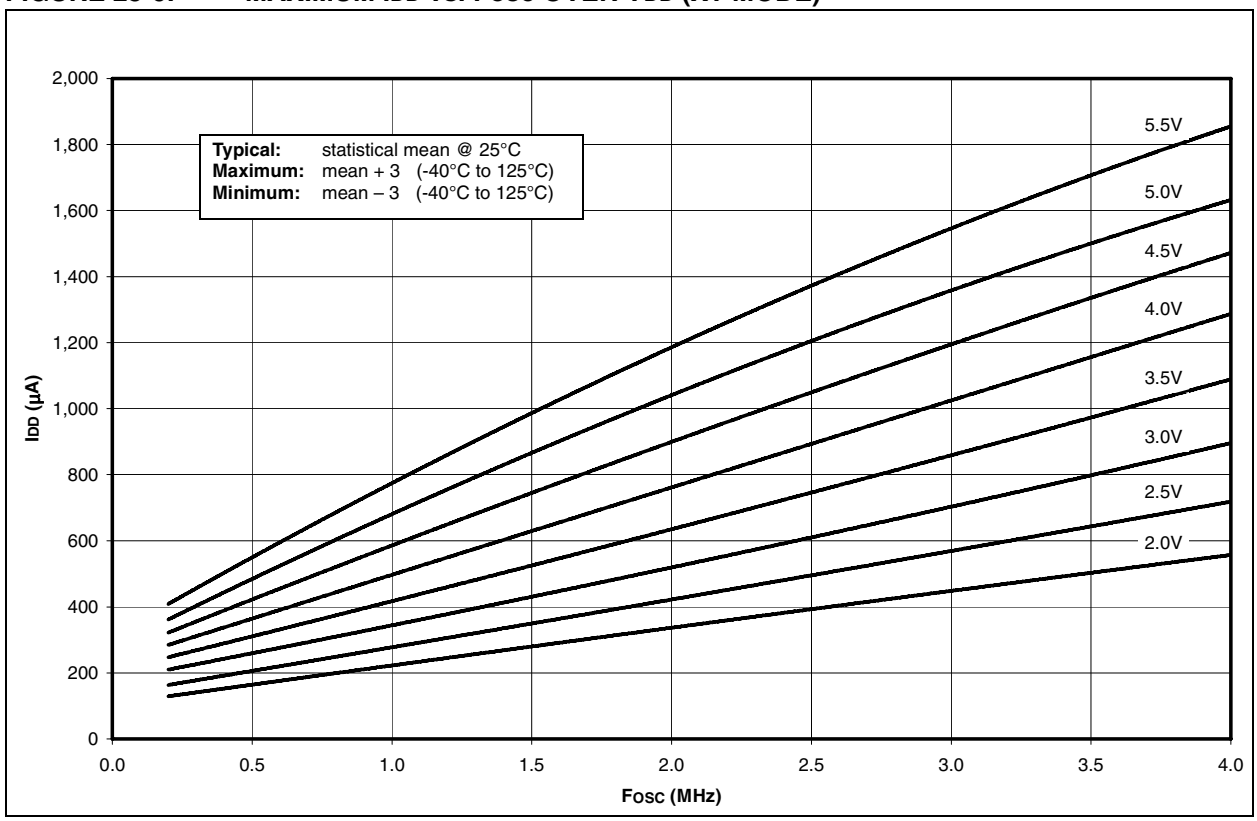


FIGURE 23-21: TYPICAL, MINIMUM AND MAXIMUM VOH vs. IOH (VDD = 5V, -40°C TO +125°C)

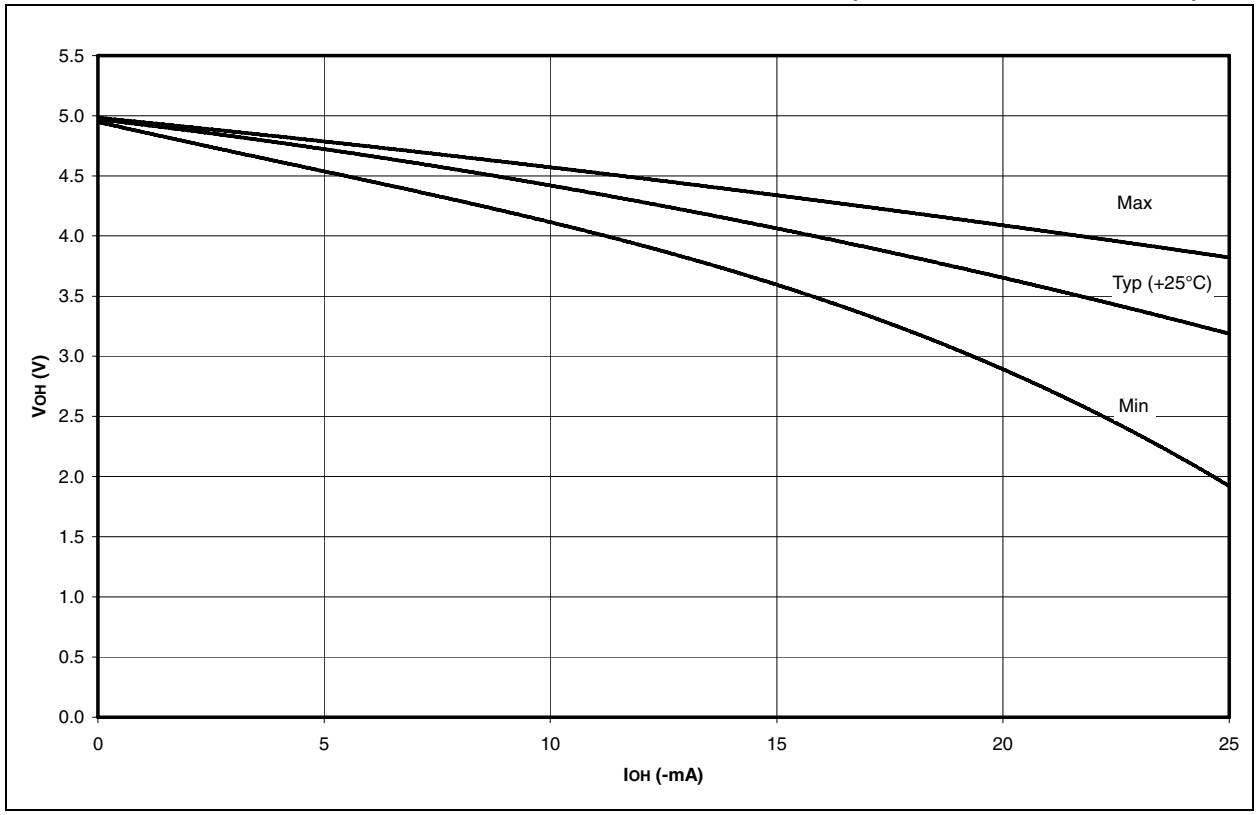
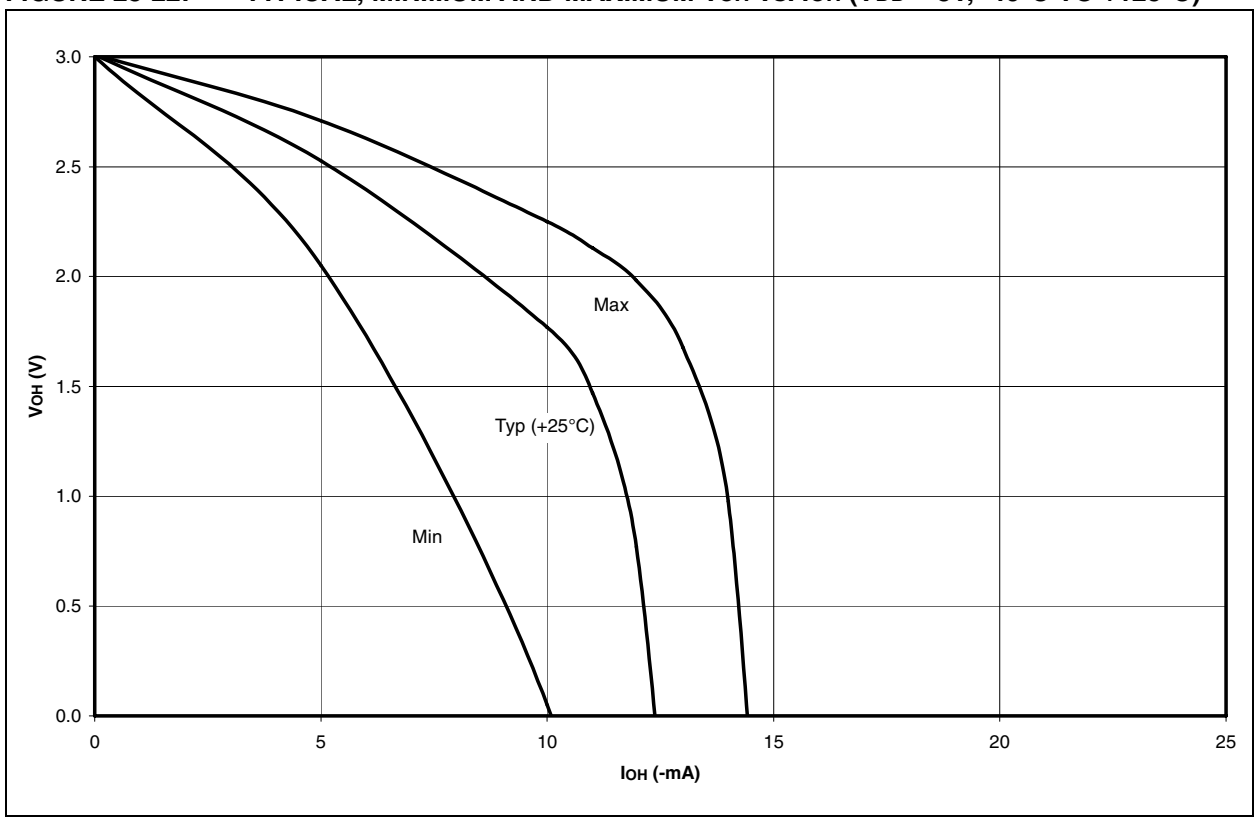
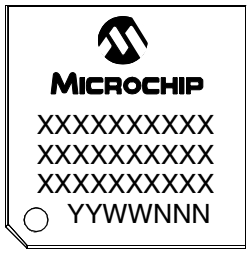


FIGURE 23-22: TYPICAL, MINIMUM AND MAXIMUM VOH vs. IOH (VDD = 3V, -40°C TO +125°C)

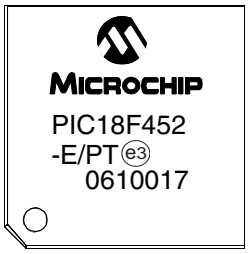


Package Marking Information (Cont'd)

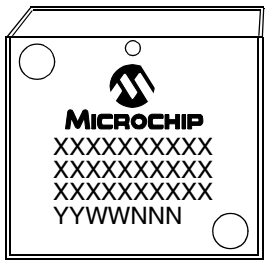
44-Lead TQFP



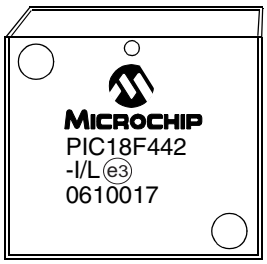
Example



44-Lead PLCC



Example

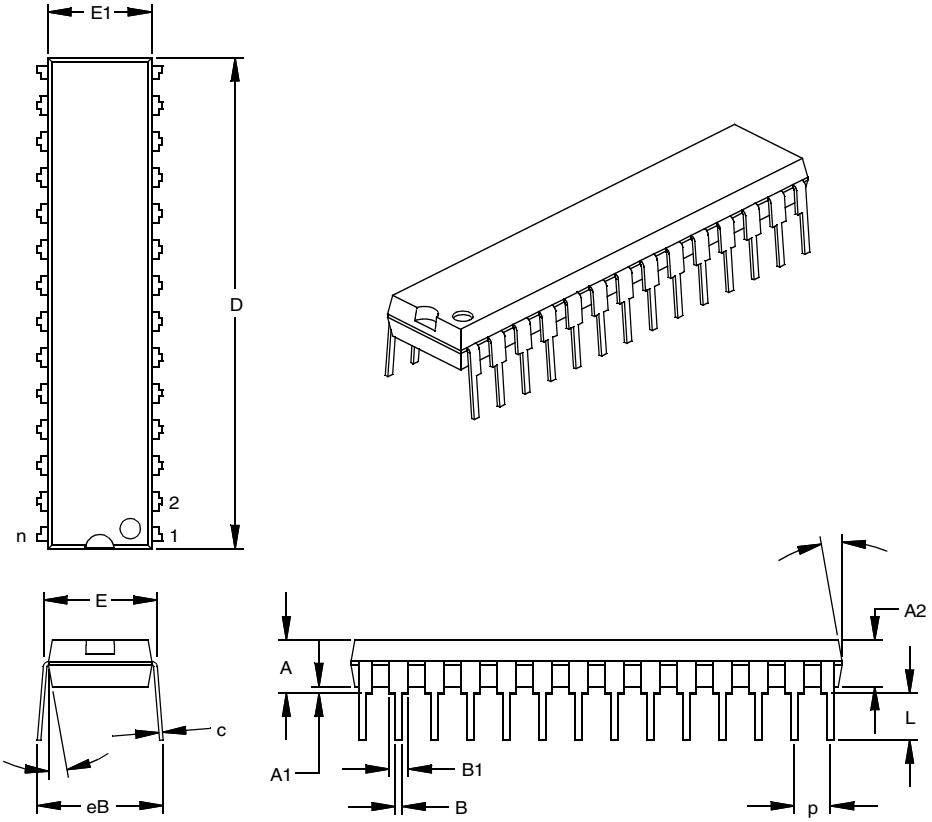


24.2 Package Details

The following sections give the technical details of the packages.

28-Lead Skinny Plastic Dual In-line (SP) – 300 mil Body (PDIP)

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging

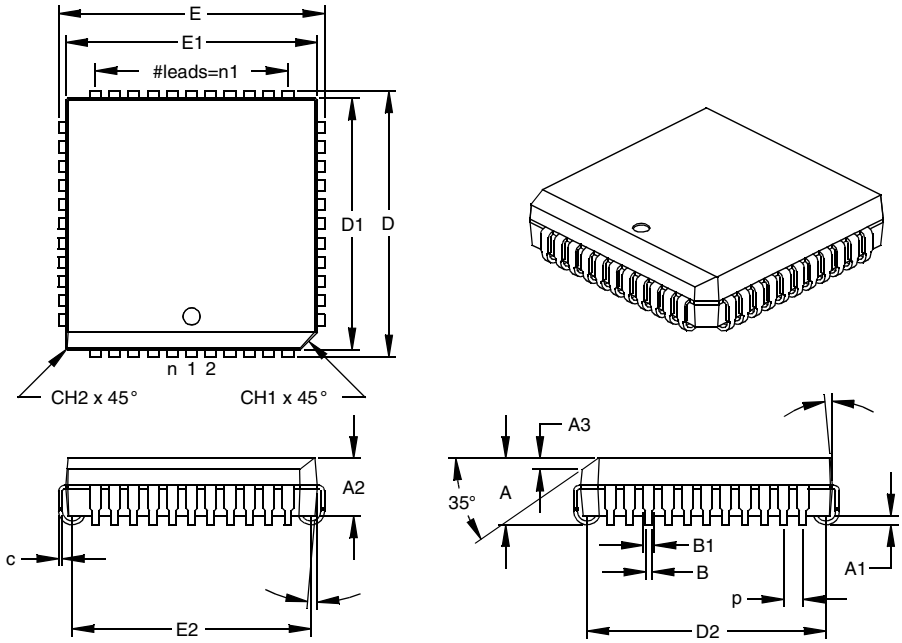


Units		INCHES*			MILLIMETERS		
Dimension Limits		MIN	NOM	MAX	MIN	NOM	MAX
Number of Pins	n		28			28	
Pitch	p		.100			2.54	
Top to Seating Plane	A	.140	.150	.160	3.56	3.81	4.06
Molded Package Thickness	A2	.125	.130	.135	3.18	3.30	3.43
Base to Seating Plane	A1	.015			0.38		
Shoulder to Shoulder Width	E	.300	.310	.325	7.62	7.87	8.26
Molded Package Width	E1	.275	.285	.295	6.99	7.24	7.49
Overall Length	D	1.345	1.365	1.385	34.16	34.67	35.18
Tip to Seating Plane	L	.125	.130	.135	3.18	3.30	3.43
Lead Thickness	c	.008	.012	.015	0.20	0.29	0.38
Upper Lead Width	B1	.040	.053	.065	1.02	1.33	1.65
Lower Lead Width	B	.016	.019	.022	0.41	0.48	0.56
Overall Row Spacing §	eB	.320	.350	.430	8.13	8.89	10.92
Mold Draft Angle Top		5	10	15	5	10	15
Mold Draft Angle Bottom		5	10	15	5	10	15

***** Controlling Parameter
§ Significant Characteristic
Notes:
Dimension D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .010” (0.254mm) per side.
JEDEC Equivalent: MO-095
Drawing No. C04-070

44-Lead Plastic Leaded Chip Carrier (L) – Square (PLCC)

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Units		INCHES*			MILLIMETERS		
Dimension Limits		MIN	NOM	MAX	MIN	NOM	MAX
Number of Pins	n		44			44	
Pitch	p		.050			1.27	
Pins per Side	n1		11			11	
Overall Height	A	.165	.173	.180	4.19	4.39	4.57
Molded Package Thickness	A2	.145	.153	.160	3.68	3.87	4.06
Standoff §	A1	.020	.028	.035	0.51	0.71	0.89
Side 1 Chamfer Height	A3	.024	.029	.034	0.61	0.74	0.86
Corner Chamfer 1	CH1	.040	.045	.050	1.02	1.14	1.27
Corner Chamfer (others)	CH2	.000	.005	.010	0.00	0.13	0.25
Overall Width	E	.685	.690	.695	17.40	17.53	17.65
Overall Length	D	.685	.690	.695	17.40	17.53	17.65
Molded Package Width	E1	.650	.653	.656	16.51	16.59	16.66
Molded Package Length	D1	.650	.653	.656	16.51	16.59	16.66
Footprint Width	E2	.590	.620	.630	14.99	15.75	16.00
Footprint Length	D2	.590	.620	.630	14.99	15.75	16.00
Lead Thickness	c	.008	.011	.013	0.20	0.27	0.33
Upper Lead Width	B1	.026	.029	.032	0.66	0.74	0.81
Lower Lead Width	B	.013	.020	.021	0.33	0.51	0.53
Mold Draft Angle Top		0	5	10	0	5	10
Mold Draft Angle Bottom		0	5	10	0	5	10

* Controlling Parameter
§ Significant Characteristic
Notes:
Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .010” (0.254mm) per side.
JEDEC Equivalent: MO-047
Drawing No. C04-048